

ENGINEERING DEPT.

REVISIONS ECN13008-0

PRODUCT SPECIFICATION

For CP35 Single Row Series Power Connector

SPEC.NO.:SPCP044BPAGE:1/6

1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and procedure with terminals crimped on the specified maximum size wire

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
MIL - STD - 1344	Test methods for electrical connectors
J-STD-020	Resistance to soldering Temperature for through hole Mounted Devices
SS-00254	Test methods for electronic components ,LEAD-FREE soldering Part design
	standards

- 3. APPLICABLE SERIES NO.: CP35 Single Row Series
- 4. SHAPE, CONSTRUCTION AND DIMENSIONS See attached drawings
- 5. MATERIALS See attached drawings
- 6. ACCOMMODATED P.C.BOARD

6.1 Thickness: 1.6 mm (.063")

6.2 P.C. Board Layout: See attached drawings



REVIEWED : <u>David</u> APPROVED : <u>Eisley</u> VERIFIED : <u>Steven</u>.



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7. ELECTRICAL PERFORMANCE:								
	ITEM	TEST CONDITION	REO	REQUIREMENT				
7.1	Rated voltage(max.)		600V AC (r.m.s.)					
		Circuits/Wire gage	2	3-6	7-12			
		AWG#20 wire gage	7.0A	5.5A	5.0A			
	Rated Current(max.)	AWG#22 wire gage	6.0A	4.5A	4.0A			
	and Applicable Wire	AWG#24 wire gage	5.5A	4.5A	3.5A			
	(Wire-to-Board)	AWG#26 wire gage	4.5A	4.0A	3.5A			
		AWG#28 wire gage	4.0A	3.0A	3.0A			
		AWG#30 wire gage	3.5A	3.0A	2.5A			
		Circuits/Wire gage						
		AWG#20 wire gage	6.5A	5.0A	4.5A			
	Rated Current(max.)	AWG#22 wire gage	5.5A	4.0A	3.5A			
	and Applicable Wire	AWG#24 wire gage	5.0A	4.0A	3.0A			
	(Wire-to-Wire)	AWG#26 wire gage	4.0A	3.0A	2.5A			
		AWG#28 wire gage	3.0A	2.0A	2.0A			
		AWG#30 wire gage	3.0A	2.0A	2.0A			
7.2	Contact resistance	Dry circuit of DC 20mV max., 100mA max., Wire resistance shell be removed from the measured value.	Less than 10 mΩ					
7.3	Dielectric strength	When applied AC 1500 V 1 minute between adjacent terminal	No Breakdown					
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More that	an 1000) ΜΩ			
7.5	Contact resistance on Crimped portion	Crimp the wire to the terminal, measure by dructic circuit, 20mV max., 100mA max., Wire resistance shall be removed from the measured value.		n 5 mΩ	2			

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Wire size	Specified wire size	Accepts AWG
			#20-#30



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	Ι	TEM	TEST CONDITION	REQUIRE	CMENT		
8.2	Terminal	crimp strength	When crimped AWG#20 size wire	More than 7.0	Kgf		
			When crimped AWG#22 size wire	More than 5.0	Kgf		
			When crimped AWG#24 size wire	More than 3.0	Kgf		
			When crimped AWG#26 size wire	More than 2.0	Kgf		
			When crimped AWG#28 size wire	More than 1.2	Kgf		
			When crimped AWG#30 size wire	More than 0.8	Kgf		
8.3 Terminal insertion force			Insertion speed 25± 3 mm per minute into housing	Less than 1.5 Kgf			
8.4	Terminal force in in		Retention speed 25± 3 mm per minute from Wire to Wire Housing	More than 2.5	Kgf		
8.5	8.5 Single contact insertion force		Measure force to insertion using mating square pin at speed 25 ± 3 mm per minute	700 gram max.			
8.6	8.6 Single contact withdrawal force		Measure force to withdrawal using mating square pin at speed 25 ± 3 mm per minute	275 gram min.			
8.7 Pin retention force in Board mount Header			Push Pin for insulator base at speed 25± 3 mm per minute	More than 1.4	Kgf		
8.8 Durability		rability Connector shall be subjected to 30 cycles of		Contact resistance:			
			insertion and withdrawal	Less than twice of initial			
8.9 Locking force			While with drawing plug & receptacle without terminal at speed 25± 3 mm per minute	More than 7.00	Kgf		

8.10 Insertion Force and Withdrawal Force :

8.10.1 Test method:

Housing with crimped contacts and a header shall be mated and unmated on the same axis. Initial insertion and withdrawal forces and withdrawal force at 30th shall be measured for single circuit and multi-circuits. For the measurement of single circuit, the housing lock shall be removed.



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8.10.2 Requirements:

Unit: Kgf

NO. OF CIRCUITS	INSERTION FORCE Max.)	WITHDRAWAL FORCE (Min.)
2	1.63	0.75
3	2.45	1.13
4	3.26	1.51
5	4.08	1.89
6	4.89	2.26
7	5.71	2.64
8	6.52	3.02
9	7.34	3.39
10	8.15	3.77
11	8.97	4.15
12	9.79	4.53

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Then carried the rated current	30°C max.
9.2	Vibration	1.5 mm 10-55-10 HZ/minute each 2 hours for X, Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.3	Heat aging	105± 2°C, 96 hours	No damage
9.4	Humidity	60± 2°C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.5	Temperature cycling	One cycle consists of : (1) -55 +0/-3 °C , 30 min. (2) Room temp. 10-15 min. (3) 105 +3/-0 °C , 30 min. (4) Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial



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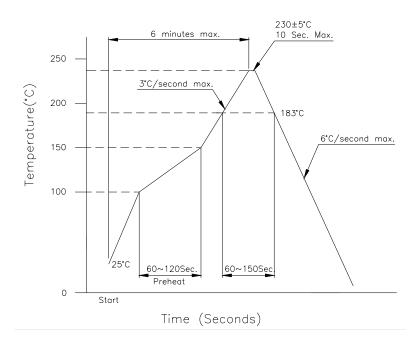
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	ITEM	TEST CONDITION	REQUIREMENT			
9.6	Salt spray	Temperature: 35± 3°C	Appearance: No damage			
		Solution: 5± 1%	Contact resistance:			
		Spray time: 48± 4 hours Measurement must be taken after water rinse	Less than twice of initial			
9.7	Solder ability	Lead-Free Process:	Minimum:			
		Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5°C	90% of immersed area			
9.8	Resistance to soldering heat	DIP Type Lead-Free Process	No damage			
		Soldering time: 5 ± 0.5 second				
		Soldering pot: 260 ± 5°C				
		SMT Type Lead-Free Process:				
		Soldering time: 20 second Max.				
		Soldering pot: 250~260°C				
		Refer Reflow temperature profile(11.2)				

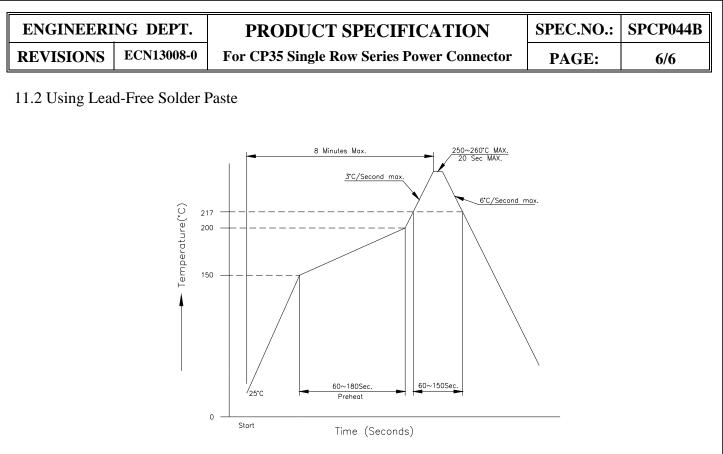
10. AMBIENT TEMPERATURE RANGE: -40 to + 105 °C

11. Recommended IR Reflow Temperature Profile:

11.1 Using Typical Solder Paste







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+	0.1	0 (44 40)	ISSUED	ENGINEER:	Sun	6/19-19'	.X ±0.30/.012	X. ± 1	MATERIAL:		DRAWING NO.	CP3512AB		CP35**S001S-NH
+	Sandy NAME	6/11-19 DATE	ECNT119143 REVISIONS	CHECKED BY: APPROVED BY:	Eisley Eisley			± *X. ± *XX.	CUSTOMER:	TCF0012	SCALE			
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